

# GSMDC4960X

## 40V N-Channel MOSFETs

### Product Description

These N-Channel enhancement mode power field effect transistors are using trench DMOS technology. This advanced technology has been especially tailored to minimize on-state resistance, provide superior switching performance, and withstand high energy pulse in the avalanche and commutation mode.

These devices are well suited for high efficiency fast switching applications.

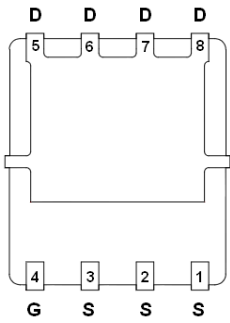
### Features

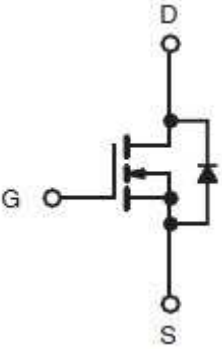
- 40V, 100A,  $R_{DS(ON)}=2.8m\Omega@V_{GS}=10V$
- Improved dv/dt capability
- Fast switching
- 100% EAS guaranteed
- Green Device Available
- DFN5X6-8L package design

### Applications

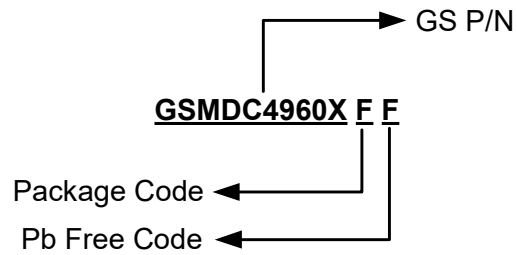
- MB / VGA / Vcore
- POL Applications
- SMPS 2<sup>nd</sup> SR

### Packages & Pin Assignments

GSMDC4960XFF (DFN5X6-8L)	
 <p>Bottom View</p>	
Pin	Description
1	Source
2	Source
3	Source
4	Gate
5	Drain
6	Drain
7	Drain
8	Drain

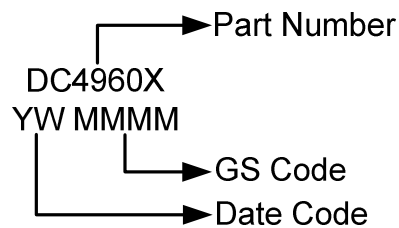


## Ordering Information



Part Number	Package	Quantity
GSMDC4960XFF	DFN5X6-8L	3000 PCS

## Marking Information



## Absolute Maximum Ratings

$T_C=25^{\circ}\text{C}$  Unless otherwise noted

Symbol	Parameter	Typical	Unit
$V_{DS}$	Drain-Source Voltage	40	V
$V_{GS}$	Gate –Source Voltage	$\pm 20$	V
$I_D$	Continuous Drain Current	$T_C=25^{\circ}\text{C}$	100
		$T_C=100^{\circ}\text{C}$	63
$I_{DM}$	Pulsed Drain Current (Note 1)	400	A
EAS	Single Pulse Avalanche Energy (Note 2)	312	mJ
IAS	Single Pulse Avalanche Current (Note 2)	79	A
$P_D$	Power Dissipation ( $T_C=25^{\circ}\text{C}$ )	135	W
	Power Dissipation (Derate above $25^{\circ}\text{C}$ )	1.08	W/ $^{\circ}\text{C}$
$T_J$	Operating Junction Temperature Range	-55 to +150	$^{\circ}\text{C}$
$T_{STG}$	Storage Temperature Range	-55 to +150	$^{\circ}\text{C}$
$R_{\theta JA}$	Thermal Resistance-Junction to Ambient	62	$^{\circ}\text{C}/\text{W}$
$R_{\theta JC}$	Thermal Resistance-Junction to Case	0.92	$^{\circ}\text{C}/\text{W}$

Note 1: Repetitive Rating: Pulsed width limited by maximum junction temperature.

Note 2:  $V_{DD}=25\text{V}$ ,  $V_{GS}=10\text{V}$ ,  $L=0.1\text{mH}$ ,  $I_{AS}=79\text{A}$ , Starting  $T_J=25^{\circ}\text{C}$ .

## Electrical Characteristics

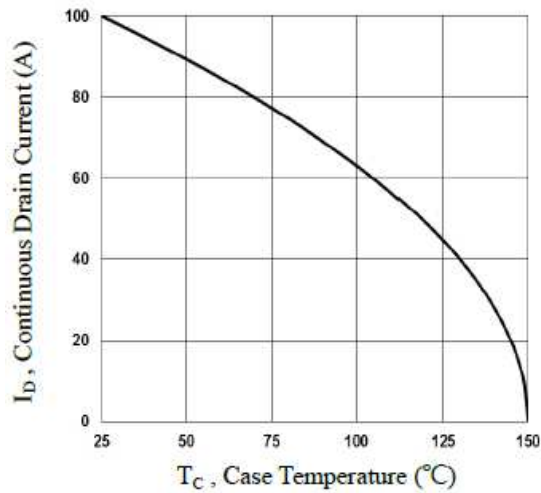
T<sub>J</sub>=25°C Unless otherwise noted

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
<b>Static</b>						
V <sub>(BR)DSS</sub>	Drain-Source Breakdown Voltage	V <sub>GS</sub> =0V, I <sub>D</sub> =250uA	40			V
ΔBV <sub>DSS</sub> /ΔT <sub>J</sub>	BV <sub>DSS</sub> Temperature Coefficient	Reference to 25°C, I <sub>D</sub> =1mA		0.03		V/°C
V <sub>GS(th)</sub>	Gate Threshold Voltage		1.2	1.6	2.5	V
ΔV <sub>GS(th)</sub>	V <sub>GS(th)</sub> Temperature Coefficient	V <sub>DS</sub> =V <sub>GS</sub> , I <sub>D</sub> =250uA		-5		mV/°C
I <sub>GSS</sub>	Gate Leakage Current	V <sub>DS</sub> =0V, V <sub>GS</sub> =±20V			±100	nA
I <sub>DSS</sub>	Zero Gate Voltage Drain Current	V <sub>DS</sub> =40V, V <sub>GS</sub> =0V			1	uA
		V <sub>DS</sub> =32V, V <sub>GS</sub> =0V, T <sub>J</sub> =125°C			10	
I <sub>S</sub>	Continuous Source Current	V <sub>G</sub> =V <sub>D</sub> =0V, Force Current			100	A
I <sub>SM</sub>	Pulsed Source Current				200	
R <sub>DS(on)</sub>	Drain-Source On-Resistance	V <sub>GS</sub> =10V, I <sub>D</sub> =25A		2.2	2.8	mΩ
		V <sub>GS</sub> =4.5V, I <sub>D</sub> =12A		2.6	3.5	
g <sub>FS</sub>	Forward Transconductance	V <sub>DS</sub> =10V, I <sub>D</sub> =2A		16		S
V <sub>SD</sub>	Diode Forward Voltage	V <sub>GS</sub> =0V, I <sub>S</sub> =1A			1	V
<b>Dynamic</b>						
Q <sub>g</sub>	Total Gate Charge (Note 3,4)			44.4	80	nC
Q <sub>gs</sub>	Gate-Source Charge (Note 3,4)	V <sub>DS</sub> =20V, V <sub>GS</sub> =4.5V, I <sub>D</sub> =10A		9.6	18	
Q <sub>gd</sub>	Gate-Drain Charge (Note 3,4)			16	30	
C <sub>iss</sub>	Input Capacitance			4940	7800	pF
C <sub>oss</sub>	Output Capacitance	V <sub>DS</sub> =25V, V <sub>GS</sub> =0V, f=1MHz		425	800	
C <sub>rss</sub>	Reverse Transfer Capacitance			170	330	
t <sub>d(on)</sub>	Turn-On Time (Note 3,4)			28	50	ns
t <sub>r</sub>				3.2	6.5	
t <sub>d(off)</sub>	Turn-Off Time (Note 3,4)	V <sub>DD</sub> =20V, I <sub>D</sub> =1A, V <sub>GS</sub> =10V, R <sub>G</sub> =6Ω		89	160	
t <sub>f</sub>				14	28	
R <sub>g</sub>	Gate Resistance	V <sub>DS</sub> =0V, V <sub>GS</sub> =0V, f=1MHz		1.4	2.8	Ω

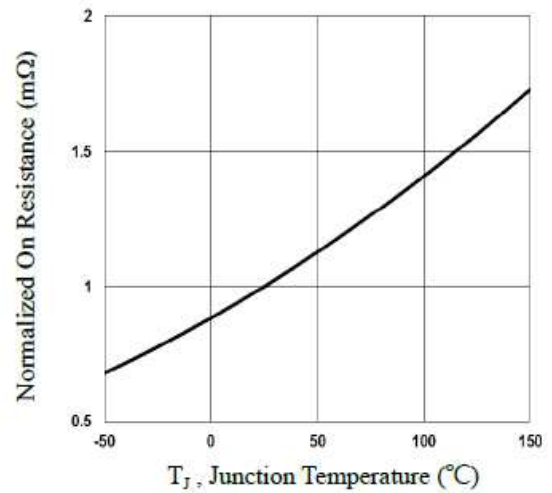
Note 3: The data tested by pulsed, pulse width ≤ 300us, duty cycle ≤ 2%.

Note 4: Essentially independent of operating temperature.

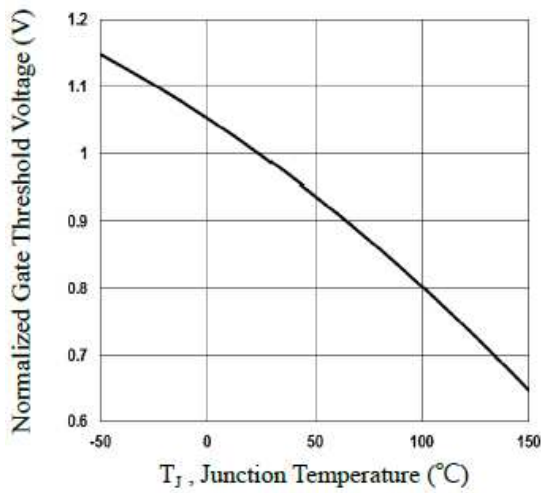
## Typical Performance Characteristics



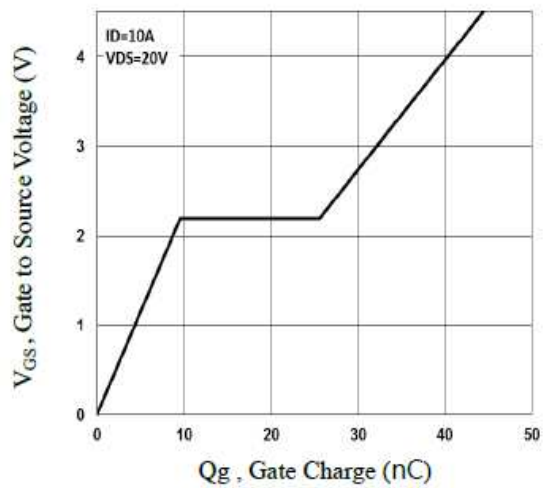
**Fig.1 Continuous Drain Current vs.  $T_C$**



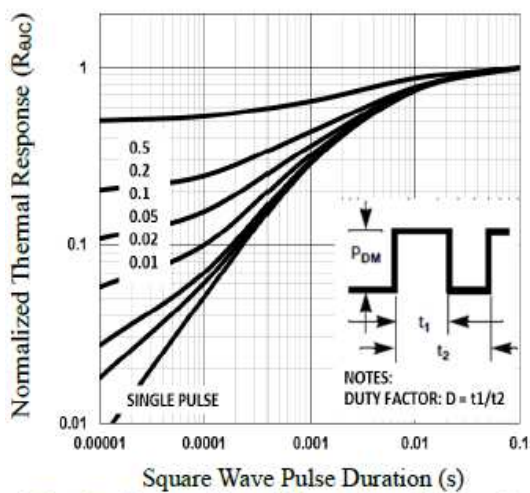
**Fig.2 Normalized  $R_{DS(on)}$  vs.  $T_J$**



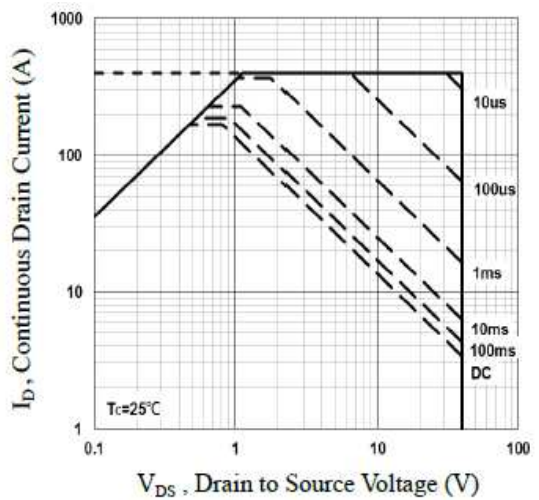
**Fig.3 Normalized  $V_{th}$  vs.  $T_J$**



**Fig.4 Gate Charge Waveform**

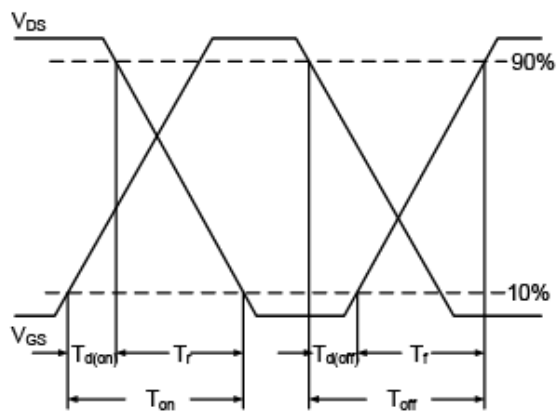


**Fig.5 Normalized Transient Impedance**

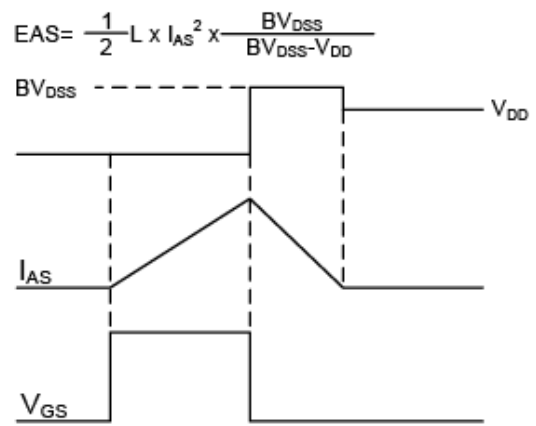


**Fig.6 Maximum Safe Operation Area**

## Typical Performance Characteristics



**Fig.7 Switching Time Waveform**

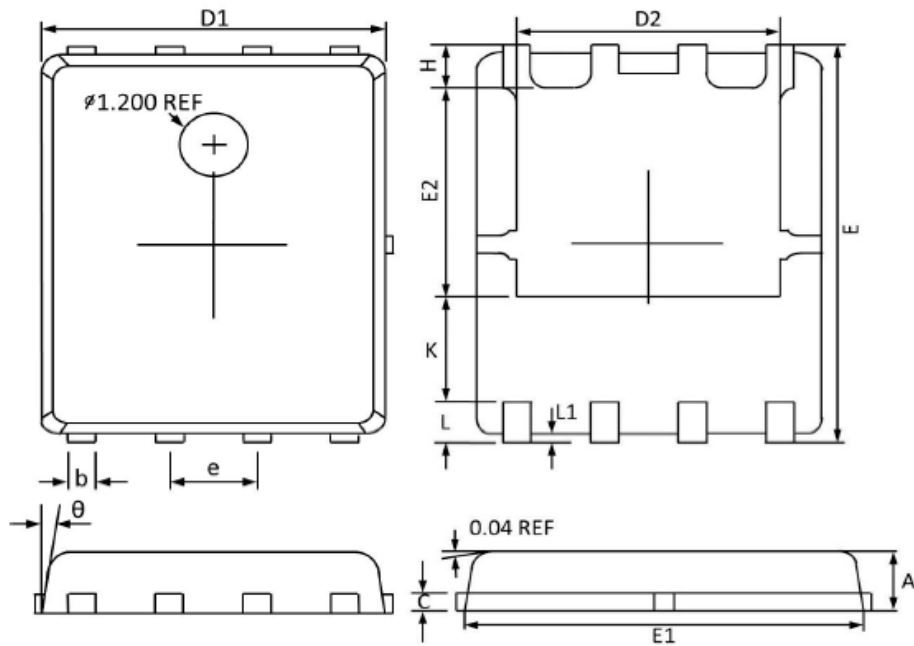


**Fig.8 EAS Waveform**

$$EAS = \frac{1}{2} L \times I_{AS}^2 \times \frac{BV_{DSS}}{BV_{DSS} - V_{DD}}$$

## Package Dimension

### DFN5X6-8L









Dimensions				
Symbol	Millimeters		Inches	
	Min	Max	Min	Max
<b>A</b>	0.900	1.100	0.036	0.043
<b>b</b>	0.330	0.510	0.013	0.020
<b>c</b>	0.200	0.300	0.008	0.011
<b>D1</b>	4.800	5.100	0.189	0.201
<b>D2</b>	3.610	4.100	0.142	0.161
<b>E</b>	5.900	6.200	0.232	0.244
<b>E1</b>	5.700	5.900	0.224	0.232
<b>E2</b>	3.350	3.780	0.132	0.149
<b>e</b>	1.270 (BSC)		0.050 (BSC)	
<b>H</b>	0.410	0.700	0.016	0.028
<b>K</b>	1.100	1.500	0.043	0.059
<b>L</b>	0.510	0.710	0.020	0.028
<b>L1</b>	0.060	0.200	0.002	0.008
<b><math>\theta</math></b>	0°	12°	0°	12°

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